

# IEEE COINS 2025

IEEE International Conference on Omni-layer Intelligent Systems

University of Wisconsin–Madison, USA | August 4-6, 2025

<https://coinsconf.com>



## Call for Papers

Are you interested in taking part in shaping and adding new dimensions to the future IoT and AI ecosystem? Do you want to stay ahead and learn about the most prominent digital technologies that are radically shifting the paradigm? Or are you just curious about what AI and AIoT are all about and how they impact every aspect of our lives, society, and business? IEEE COINS (<https://coinsconf.com>) is the right place to be. IEEE COINS brings together experts in Digital Transformation (from AI to IoT, Cloud Computing, low power design, security, privacy, and robotics) from around the globe.

IEEE COINS includes a multi-disciplinary program, from technical research papers to panels, workshops, and tutorials on the latest technology developments and innovations. IEEE COINS will address all important aspects of the of the AI/AIoT ecosystem. IEEE COINS solicits papers and proposals accompanying submissions for presentations in the following topical and vertical tracks:

### Topical Area Tracks

1. Internet of Things: From Edge to Cloud
2. Sensing Devices and Systems for AIoT
3. Circuits and Systems (CAS) Designs AIoT
4. Communications and Networking for AIoT
5. Artificial Intelligence, Machine Learning, and Cognitive Computing
6. Distributed Ledger Technologies and Blockchain
7. Low Power Design and Automation
8. Security and Privacy
9. Intelligent Robots and Systems
10. Embedded AI

### Important Dates:

- Paper submission: 29 April 2025
- Special session, workshop, tutorial proposal: 29 April 2025
- Acceptance notification: 31 May 2025
- Camera-ready submission: 21 June 2025

### Vertical Tracks

1. Smart Infrastructure
  - Smart City
  - Energy and Smart Grids
  - Smart Agriculture
  - Smart Mobility, Transportation, and Logistics
2. Industry 4.0 and Smart Manufacturing
3. Digital Healthcare and Well-being

### Special Tracks

1. Emerging Technologies on Intelligent Systems
2. Generative AI: Systems, Architectures, and Applications

### Panels

1. Engagement and Outreach Program
2. Industrial Talks
3. Workshops/Tutorials